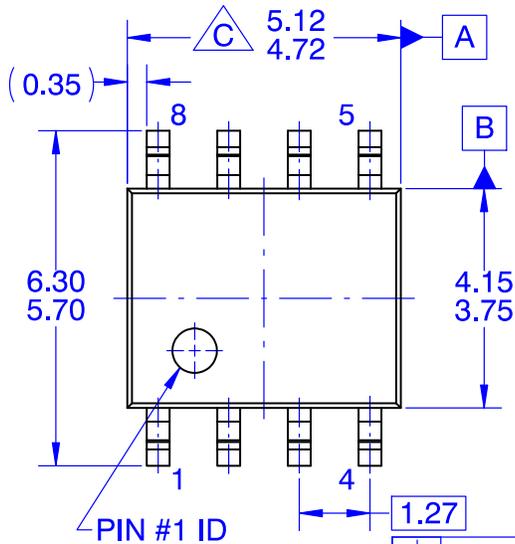
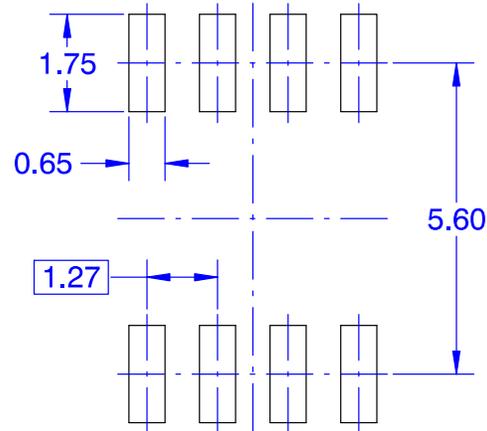


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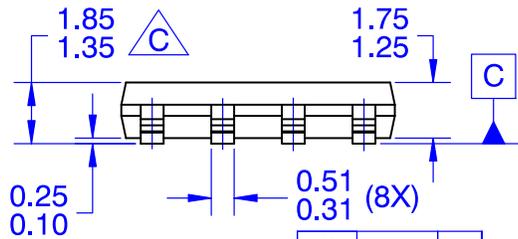
DATE 30 SEP 2016



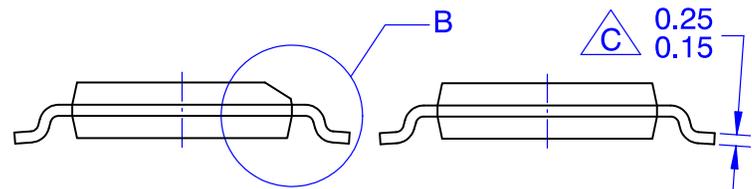
TOP VIEW



LAND PATTERN RECOMMENDATION



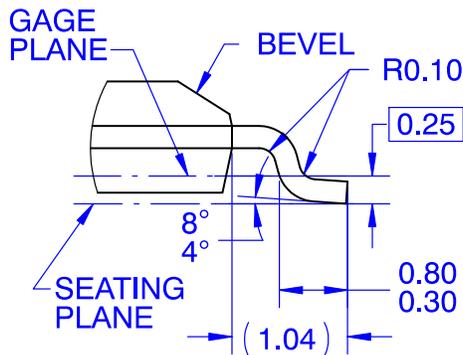
FRONT VIEW



OPTION A
BEVEL EDGE

OPTION B
NON-BEVEL EDGE

SIDE VIEW



DETAIL "B"
SCALE 2:1

NOTES: UNLESS OTHERWISE SPECIFIED

- A. THIS PACKAGE CONFORMS TO JEDEC MS-012 VARIATION A EXCEPT WHERE NOTED.
- B. ALL DIMENSIONS ARE IN MILLIMETERS
- $\triangle C$ OUT OF JEDEC STANDARD VALUE
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- E. LAND PATTERN AS PER IPC SOIC127P600X175-8M

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